NEI	Work Inst	ruction	Page 1 of 21
Title:			
Unit Dis	assembly for W	/EEE	
Document Number / Disk File:	By:	Current Rev:	Date:
597-786-0155-01 Tim Connolly 0B			03/26/2012
Assemblies Covered:			
E-1	800R2 (786-0155-XX)		



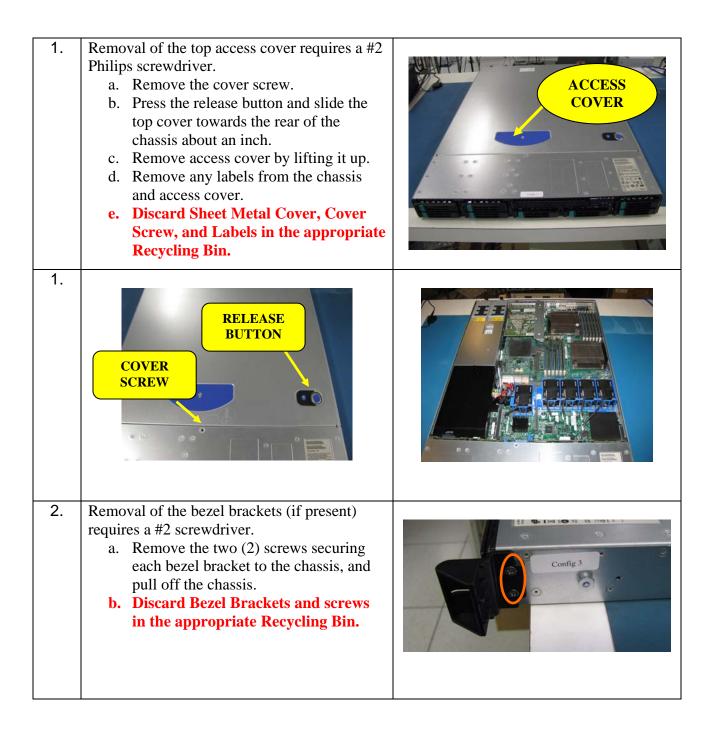
Revision	Date	ECO #	Revised By	Description of Changes
0A	July 28, 2009	L1881	T. Connolly	Initial Release
0B	March 26, 2012	E01688	T. Connolly	Added step for EMI Gasket removal

Tools Required:

- #2 Phillips Screwdriver
- #1 Phillips Screwdriver
- Needle nose Pliers

NEI	Work Inst	ruction	Page 2 of 21
Title: Unit I	Disassembly for W	VEEE	
Document Number / Disk File:	By:	Current Rev:	Date:
597-786-0155-01 Tim Connolly 0B			03/26/2012
Assemblies Covered:			·
	E-1800R2 (786-0155-XX)		

NOTE : Disconnect any AC Power Cords attached to the power supplies before disassembly of the unit.



	NEI	Work Inst	ruction	Page 3 of 21	
	Title: Unit Disassembly for WEEE				
	Document Number / Disk File: 597-786-0155-01	By: Tim Connolly	Current Rev: 0B	Date: 03/26/2012	
	Assemblies Covered: E-18001	R2 (786-0155-XX)			
3.	 Removal of the Power Supply (ies) does require any tools. a. Press and hold the green button to the power supply handle. b. Pull the supply straight out of the root of the chassis. c. Discard the Power Supply (ies) in appropriate Recycling Bin. 	wards rear			
4.	Removal of the Remote Management Ma (if present) requires a #2 Phillips screwd a. Remove the two (2) screws securi the module to the rear of the chass b. Disconnect the module cable from motherboard, and lift the module the chassis.	river. ing sis. n the			
4.	 c. Remove the cable connected to the module. d. Remove the three (3) screws secutive the module bracket to the module e. Discard the Remote Managemer Module, cable, bracket, and screwing the appropriate Recycling Bit in the appropriate R	ring nt ews			

	NEI	Work Insti	uction	Page 4 of 21
	Title: Unit Disassembly for WEEE			
-	Document Number / Disk File: 597-786-0155-01 Assemblies Covered:	^{By:} Tim Connolly	Current Rev: 0B	Date: 03/26/2012
		R2 (786-0155-XX)		
5.	Removal of the PCI card assembly does require any tools. a. Remove the PCI card by lifting it straight out of the chassis.		10002255	PCI Card Assembly
6.	 Removal of the PCI card (if installed) rea a #2 Phillips screw driver. a. Remove the PCI riser card from the motherboard by removing the screw securing the card to the bracket and pulling out away from the riser. b. Discard the PCI card and screw the appropriate Recycling Bin. 	he ew nd		Screw
7.	 Removal of the EMI gaskets (if installed does not require any tools. a) Remove the two EMI gaskets from PCI bracket by peeling them off. b) Discard the EMI gaskets in the appropriate Recycling Bin. 	om the		EMI Gaskets

	NEI	Work Inst	ruction	Page 5 of 21
	Title: Unit Disas	/EEE		
	Document Number / Disk File: 597-786-0155-01 Assemblies Covered:	^{By:} Tim Connolly	Current Rev: 0B	Date: 03/26/2012
	E-18001	R2 (786-0155-XX)		
8.	 Removal of the PCI riser card (if installer requires a #2 Phillips screw driver. a. Remove the PCI riser card from the bracket by removing the two screwand lifting off. b. Discard the PCI riser card, brack and screws in the appropriate Recycling Bin. 	ne ws	Scr	ews
9.	 Removal of the Air Duct does not requir tools. a. Remove the Air Duct by lifting it straight up and out of the chassis. b. Discard the Air Duct in the appropriate Recycling Bin. 	AAA		Air Duct
10.	 Removal of the Power Distribution Boar Cover requires a #2 Philips screwdriver. a. Remove the screw securing the conthe chassis. b. Lift the cover straight up and out of chassis to complete removal. c. Discard the Power Distribution Board Cover in the appropriate Recycling Bin. 	ver to of the	Screw	

	NEI	Work Instruction	Page 6 of 21			
	Title: Unit Disassembly for WEEE					
	Document Number / Disk File: 597-786-0155-01	By:Current Rev:Tim Connolly0B	Date: 03/26/2012			
	Assemblies Covered: E-1800E	R2 (786-0155-XX)				
11.	 Removal of the Power Distribution Board does not require any tools. a. Disconnect all power cables from surrounding powers (three on the motherboard, one on the mid-plan and one on the backplane). b. Slide the Power Distribution Board the right, and lift out of the chass c. Discard the Power Distribution Board in the appropriate Recycle Bin. 	a the ne, rd to is. Power Connections				
12.	 Removal of the Battery Backup (if present does not require any tools. a. Disconnect the battery cable from the mid-plane. b. Slide the battery towards the fron of the chassis about half an inch, and it out of the chassis. c. Open the battery case, and disconnect the external cable, and the cable going from the battery pack to the battery controller board. d. Discard the Battery Pack, the Controller Board, the Battery Caand cables in the appropriate Recycling Bin. 	he Battery Backup ect	Battery Cable			
13.	 Removal of the Bridge Board does not require any tools. a. Open the retention clips of the Bridge Board on the mid-plane, an motherboard. b. Pull the Bridge Board straight up t remove. c. Discard the Bridge Board in the appropriate Recycling Bin. 					

	NEI Work Instruction		Page 7 of 21		
	Title: Unit Disassembly for WEEE				
	Document Number / Disk File: 597-786-0155-01	By: Tim Connolly	Current Rev: 0B	Date: 03/26/2012	
	Assemblies Covered: E-1800	R2 (786-0155-XX)			
E					
13.					
14.	 Removal of the Fan Assembly does not require any tools. a. Disconnect all fan power cables frithe mid-plane. b. Press the latch on the side of the F Assembly and slide the assembly it the left. c. Carefully pick up the assembly an remove from the chassis. d. Fans can be lifted straight out of the assembly. e. Discard the Fan Assembly and fans in the appropriate Recyclin Bin 	an to d he Fan Assembly			

	NEI	Work Instruction	Page 8 of 21
	Title: Unit Disas	sembly for WEEE	
	Document Number / Disk File: 597-786-0155-01	By:Current Rev:Tim Connolly0B	Date: 03/26/2012
	Assemblies Covered: E-1800	R2 (786-0155-XX)	
15.	 Removal of the RAID Mini DIMM and RAID Activation Key does not require an tools. a. Push the retaining clips on the RA Mini DIMM away from the DIMM b. Pull the DIMM away from the connector to remove. c. Push the tabs to the sides of the Activation Key and lift the key ou its connector. d. Discard the RAID Mini DIMM and RAID Activation Key in the appropriate Recycling Bin. 	ID A. t of	ivation Key
16.	 Removal of the Active Mid-Plane require #2 Philips screwdriver. a. Remove the screw securing the Active Mid-Plane to the chassis. b. Slide the mid-plane towards the ba of the chassis, making sure the contacts in the backplane are fully out. c. Life the mid-plane up and out of the chassis. d. Discard the Active Mid-Plane and screw in the appropriate Recycle Bin. 	ack he he he	
16.			

	NEI	Work Inst	ruction	Page 9 of 21		
ŀ	Title:			1		
	Unit Disassembly for WEEE					
	Document Number / Disk File:	By:	Current Rev:	Date:		
	597-786-0155-01 Assemblies Covered:	Tim Connolly	0B	03/26/2012		
		R2 (786-0155-XX)				
L	2 2000	(100 0100 111)				
17.	 Removal of the CPU Heatsink(s) requires #2 Philips screwdriver. a. Start loosening the four (4) screws each heatsink two turns at a time in the order shown in the picture belob. b. Once all screws are fully out, life theatsinks out of the chassis. c. Discard the Heatsink(s) in the appropriate Recycling Bin. 	a of n ow. the	eatsinks			
17.						

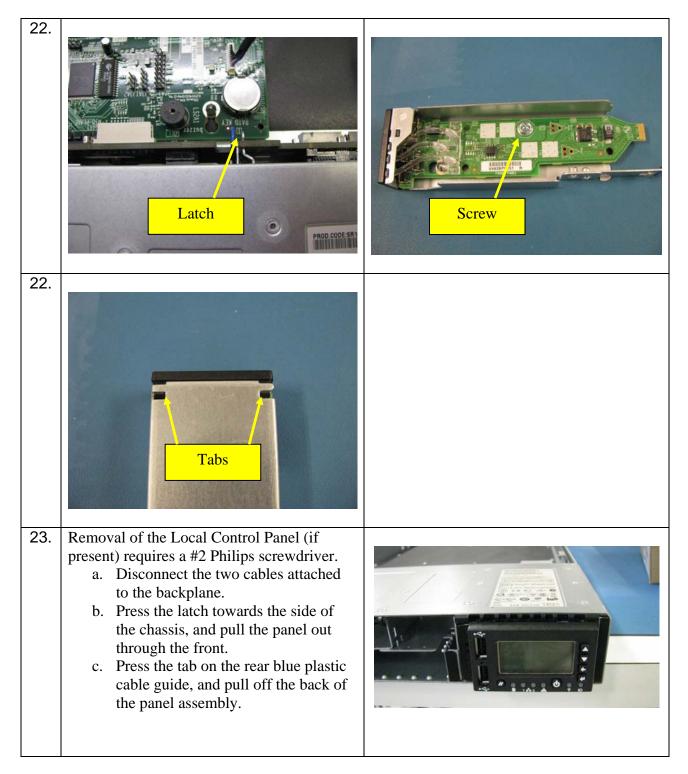
	NEI	Work Instr	uction	Page 10 of 21
	Title: Unit Disas	EEE		
	Document Number / Disk File: 597-786-0155-01	Current Rev: 0B	Date: 03/26/2012	
•	Assemblies Covered:	R2 (786-0155-XX)		
18.	 Removal of the CPU(s) does not require a tools. a. Push the latch down and then away from the CPU socket. b. Open the load plate, and carefully remove the CPU from its socket. c. Discard the CPU(s) in the appropriate Recycling Bin. 	3		ch
19.	 Removal of the Memory DIMMs and Lithium Battery from the motherboard do not require any tools. a. Remove each of the Memory DIM by pushing down and out on the tw latches, one on each end of the DIMM connector. Lift memory DIMM straight out to remove. b. Remove the coin style Lithium Battery. c. Discard the Memory DIMMs and Lithium Battery in the appropria Recycling Bin. *** CAUTION *** Care should be observed when disposin of the battery to avoid shorting it! 	Ms o h te		

	NEI	Work Instru	iction	Page 11 of 21
	Title: Unit Disassembly for WEEE			
-	Document Number / Disk File: 597-786-0155-01		Current Rev: 0B	Date: 03/26/2012
	Assemblies Covered: E-1800E	R2 (786-0155-XX)		
20.	Removal of the Optical Drive (if present)			
20.	 Removal of the Optical Drive (if present) requires a #2 Philips screwdriver. a. Press the tab on the plastic guide behind the backplane, and pull the drive straight out of the chassis. b. Remove the two (2) screws securin the blue tab to the rear of the drive c. Discard the Optical Drive, Plastiguide, and screws in the appropriate Recycling Bin. 	ng		
20.	Latch			

	NEI	Work Instr	uction	Page 12 of 21
-	Title: Unit Disassembly for WEEE			
	Document Number / Disk File: 597-786-0155-01		Current Rev: 0B	Date: 03/26/2012
-	Assemblies Covered:	Thin Connorry	UD	03/20/2012
	E-1800]	R2 (786-0155-XX)		
21.	Removal of the Hard Drive (s) requires a Philips screwdriver. a. Press the tab on the front of the dr carrier, and pull the drive straight of the chassis.	ive		
21.	 b. Remove the four (4) screws securities the drive to the carrier (two on each side). (repeat for each drive install c. Discard the Hard Drive(s), Carriers, and screws in the appropriate Recycling Bin. 	h		
22.	 Removal of the Mini Control Panel (if present) requires a #2 Philips screwdriver a. Press the latch at the rear of the M Control Panel, and push it towards the front of the chassis. b. Slide the panel out of the chassis. c. Remove the screw securing the control board to the panel bracket. d. Press the panel bezel tabs on the underside of the bezel bracket, and pull the bezel off. e. Discard the Mini Control Panel, control board, bezel, panel bracket, and screw in the appropriate Recycling Bin. 	ini Salari 1	D A	

NEI	Work Inst	ruction	Page 13 of 21
Title:			
Unit	Disassembly for V	VEEE	
Document Number / Disk File:	By:	Current Rev:	Date:
597-786-0155-01	Tim Connolly	0B	03/26/2012
Assemblies Covered:			·
	E 1000D3 (70(0155 VV)		





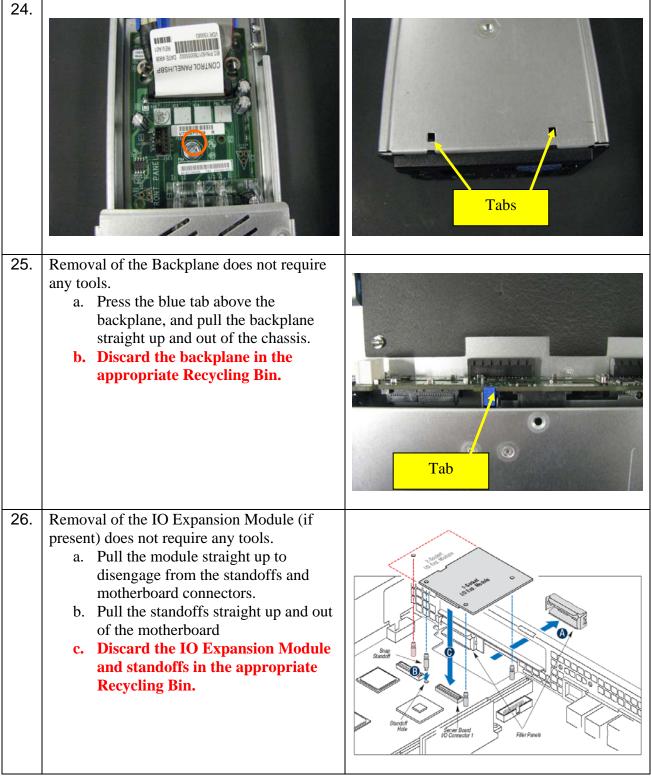
	NEI	Work Instr	uction	Page 14 of 21
	Title: Unit Disass	sembly for W		
	Document Number / Disk File:	By:	Current Rev:	Date:
	597-786-0155-01	Tim Connolly	0B	03/26/2012
	Assemblies Covered:	00 (706 0155 VV)		
<u> </u>	E-1800F	R2 (786-0155-XX)		
23.	 d. Remove the screw on the rear of the panel assembly. e. Disconnect and remove the cables from the controller board and LCD f. Remove the screw from the controller board and pull out of the assembly. g. Remove the two screws from the LCD and pull out of the assembly 			Cables
23.	 h. Press in the two bezel clips on the bottom of the panel assembly and pull off the bezel. i. Discard the LCD, Plastic cable guide, brackets, controller board cables, and screws in the appropriate Recycling Bin. 	,	Cable Gu	ide
23.				15330109601 A01

NEI	Work Inst	ruction	Page 15 of 21	
Title:	isassembly for V	VEEE		
Document Number / Disk File:		Current Rev:	Date:	
597-786-0155-01	Tim Connolly	0B	03/26/2012	
Assemblies Covered:				
E-1800R2 (786-0155-XX)				

23.	Tabs	
24.	 Removal of the Standard Control Panel (if present) requires a #2 Philips screwdriver. a. Disconnect the two cables attached to the backplane. b. Press the latch towards the side of the chassis, and pull the panel out through the front. c. Remove the two cables connected to the panel board. Remove the screw holding the panel board to the panel assembly, and pull the board out. 	
24.	 d. Press the two clips on the bottom of the panel assembly and remove the bezel. e. Discard the bezel, panel board, bracket, cables, and screws in the appropriate Recycling Bin. 	And a state of the

NEI	Work Inst	ruction	Page 16 of 21
Title: Unit	Disassembly for V	VEEE	
Document Number / Disk File:	By:	Current Rev:	Date:
597-786-0155-01	Tim Connolly	0B	03/26/2012
Assemblies Covered:			
F-1800R2 (786-0155-XX)			





NEI	Work Inst	ruction	Page 17 of 21	
Title:				
Unit I	Disassembly for W	/EEE		
Document Number / Disk File:	By:	Current Rev:	Date:	
597-786-0155-01	Tim Connolly	0B	03/26/2012	
Assemblies Covered:				
E-1800R2 (786-0155-XX)				

NEI	Work Inst	ruction	Page 18 of 21
Title:			
Unit E	Disassembly for W	/EEE	
Document Number / Disk File:	By:	Current Rev:	Date:
597-786-0155-01	Tim Connolly	0B	03/26/2012
Assemblies Covered:			
	F 1900D2 (786 0155 VV)		

E-1800K2 (786-0155-XX)

Fully Disassembled Unit

DISCARD THE FULLY DISASSEMBLED UNIT IN THE APPROPRIATE RECYCLE BIN.



NEI	Work Inst	truction	Page 19 of 21
Title: Unit Disa	ssembly for \	NEEE	
Document Number / Disk File:	By:	Current Rev:	Date:
597-786-0155-01	Tim Connolly	0B	03/26/2012
Assemblies Covered:			
E-1800R2 (786-0155-XX)			

Recycling/Material Code	Important Information
Material /Components, which must be remov	ed and treated separately
Lithium Battery	Battery free of hazardous substances, installed in socket on the motherboard
Lithium Ion RAID Battery Backup	Battery is RoHS 5/6, installed beside the active mid-plane
RAID Activation Key	RAID Activation Key free of hazardous substances, installed in socket on the mid-plane
** LCD-Display	LCD control board background lighting contains Hg
Printed circuit boards	Motherboard, DIMMs, PCI card, PCI riser, Power Supply, Active Mid-Plane, Backplane, RAID DIMM, Power Distribution Board, IO Expansion Module, Remote Management Module, Bridge Board, & Front Panel Control Board
Disk Drives	Mounted on disk carrier
Material /Components, which can disturb cen	tain recycling processes
Copper	Fansink
Material /Components, through which benefi	ts can normally be achieved
Cold Rolled Steel	Fixed cover, PCI bracket, & chassis
* ABS	Bezel, Control Panel Bezel, Cable Guide, Power Distribution Board Cover, Fan Assembly, & Air Baffle
Cables	Distributed in device & power cord
Fans	Fan Assembly
Special notes	
** LCD display background lights contain Hg. * Flame retardant of plastics do not contain PBI	3 and PBDE.

NEI	Work Inst	ruction	Page 20 of 21
Title: Unit	Disassembly for W	VEEE	
Document Number / Disk File: 597-786-0155-01	By: Tim Connolly	Current Rev: 0B	Date: 03/26/2012
Assemblies Covered: E-1800R2 (786-0155-XX)			

Annex A

Producer:	<company addressing="" name,="" on="" other="" producer="" the=""></company>	
Scope of information sheet:	< product category as in Annex IA of WEEE Directive, or type of equipment as in Annex 1B of WEEE Directive, or producer's Product Family, or single products identified by brand and model name >	

Component or Material	Remarks / Location	
Battery (internal *) containing Mercury (Hg)/ NiCad/Lithium/	Lithium battery 📕	
Other	located on the motherboard	
Backlighting lamps of LCD/TFT or similar screens containing Mercury (Hg)	NONE	
Mercury (Hg) in other applications**	NONE	
Cadmium**	NONE	
Gas discharge lamps	NONE	
Plastic containing brominated flame retardants other than in Printed Circuit Assemblies ***	NONE	
Liquid Crystal Displays with a surface greater than 100 cm2	NONE	
Capacitors with PCB's	NONE	
Capacitors with substances of concern**** + height > 25 mm, diameter > 25 mm or proportionately similar volume	NONE	
Asbestos	NONE	
Refractory ceramic fibres	NONE	
Radio-active substances	NONE	
Beryllium Oxide	NONE	
Other forms of Beryllium	BE-CU in some connector contacts	
Gasses - which fall under Regulation (EC) 2037/2000 and all hydrocarbons (HC).	NONE	
Components with pressurised gas which need special attention (Pressure > 1,5 bar) *****	NONE	
Liquids ***** if volume > 10 cl (or equivalence in weight, e.g. for PCB, oil)	NONE	
Mechanical components that store mechanical energy (i.e. springs) or equivalent parts which need special attention ***** (diameter > 10 mm and height > 25 mm or proportionally similar volume and expanding)	NONE	
PBDE (deca- & octa-BDE) and Perfluorocatane sulfantes (PFOS) in Directive 2006/122/EC	NONE	

NEI Work Instruction		Page 21 of 21		
Title: Unit Disassembly for WEEE				
Document Number / Disk File: 597-786-0155-01	By: Tim Connolly	Current Rev: 0B	Date: 03/26/2012	
Assemblies Covered: E-1800R2 (786-0155-XX)				

= arrow indicates the need for the location of the compartment/ substances within the product. When the location of a substance/ components is requested, it is at part level, e.g. main board, housing etc

* Internal means that batteries can only be removed by opening the product by means of (a) tool(s).

** Substances are considered to be in the product if present above the levels specified in Commission Decision 2005/618/EC related to Directive 2002/95/(EC) (RoHS Directive) or if their use is permitted through exemptions in the Annex of Directive 2002/95(EC)

*** To be coherent with industry current standards and practices on tracking of plastic parts, Directive 2002/96 (EC) Annex II requirement is understood to focus on plastic parts that weight more than 25 g.

**** Substance of concern other than PCB, to be specified/ addressed further in the context of Directive 2002/96 (EC) Annex II national requirements and European developments

**** Needs of equivalent nature as those for maintenance, service manuals and installation for safety purposes.